

Copper

SLOTOCOUP XF 60

Copper electrolyte based on sulfuric acid, for the filling of Blind Microvias with aspect ratios > 1 and with a very thin surface layer thickness (< 5 µm) for 5G applications, meets all the usual process test standards.

APPLICATION

- mSAP
- SAP
- HDI

PROCESS

- Pattern- and panel plating
- VCP- and standard vertical plating lines
- insoluble MMO anodes
- The system is operated with three additives.

BENEFITS

- SLOTOCOUP XF 60 can be applied as a single process or in the IT1 process.
- The IT1 process describes a process sequence of
 - Direct Metallisation (SLOTOGO PCB 3700)
 - Flash Via Filling (SLOTOCOUP XF 60)
 - Pattern plating with Pulse plating (e.g. SLOTOCOUP PRT 2200, SLOTOCOUP CU 210).
- low surface layer thickness
- uniform distribution of the surface layer thickness

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

